TOSHIBA Bi-CMOS Integrated Circuit Silicon Monolithic

# **TB62777FNG, TB62777FG**

8-Channel Constant-Current LED Driver of the 3.3-V and 5-V Power Supply Voltage Operation

The TB62777FNG/FG is comprised of constant-current drivers designed for LEDs and LED panel displays.

The regulated current sources are designed to provide a constant current, which is adjustable through one external resistor.

The TB62777FNG/FG incorporates eight channels of shift registers, latches, AND gates and constant-current outputs.

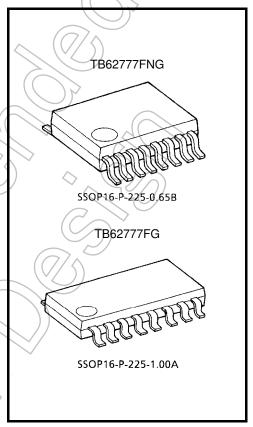
Fabricated using the Bi-CMOS process, the TB62777FNG/FG is capable of high-speed data transfers.

The TB62777FNG/FG is RoHS.

### **Features**

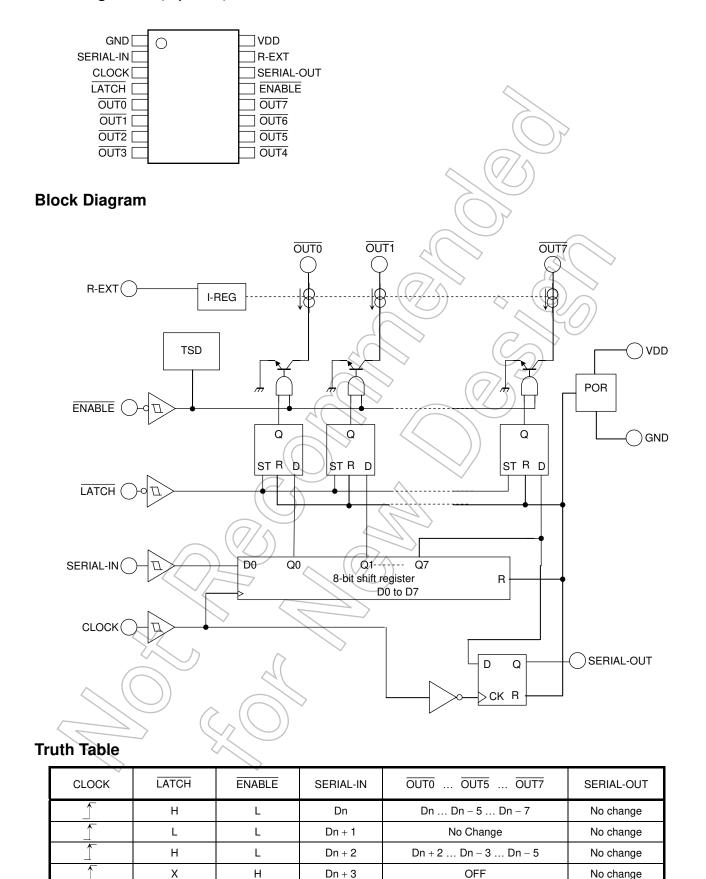
- Power supply voltages: V<sub>DD</sub> = 3.3 V/5 V
- Output drive capability and output count: 50 mA × 8 channels
- Constant-current output range: 5 to 40 mA
- Voltage applied to constant-current output terminals: 0.4 V (min, IOUT = 5 to 40 mA)
- Designed for common-anode LEDs
- Thermal shutdown (TSD) (min: 150°C)
- Power on reset (POR)
- Logical input signal voltage level: 3.3-V and 5-V CMOS interfaces (Schmitt trigger input)
- Maximum output voltage: 25V
- Serial data transfer rate: 25 MHz (max) @cascade connection
- Operating temperature range:  $T_{opr} = -40$  to  $85^{\circ}C$
- Package: SSOP16-P-225-0.65B/ SSOP16-P-225-1.00A
- Constant-current accuracy

Output Voltage	Current accuracy Between Channels	Current Accuracy Between ICs	Output Current
0.4 V to 4 V	±3%	±6%	15 mA



Weight: SSOP16-P-225-0.65B 0.07 g (typ.) SSOP16-P-225-1.00A 0.14 g (typ.)

### Pin Assignment (top view)



Note 1:  $\overline{OUT0}$  to  $\overline{OUT7}$  = On when Dn = H;  $\overline{OUT0}$  to  $\overline{OUT7}$  = Off when Dn = L.

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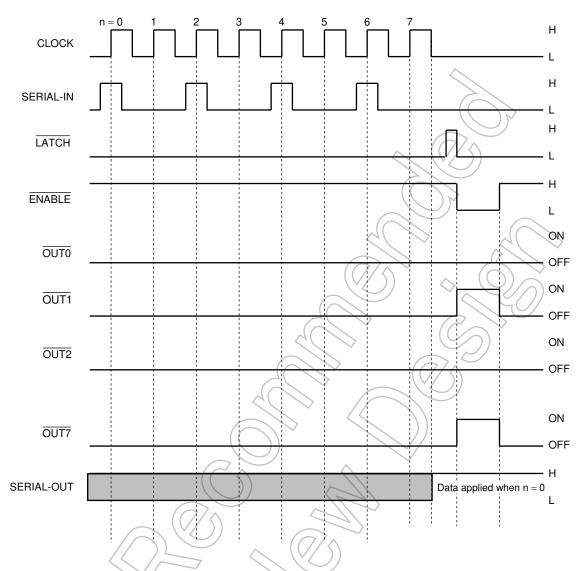
Dn + 3

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OFF

Dn −4

### **Timing Diagram**



Note 1: Latches are level-sensitive, not edge-triggered.

Note 2: The TB62777FNG can be used at 3.3 V or 5.0 V. However, the V<sub>DD</sub> supply voltage must be equal to the input voltage.

Note 3: Serial data is shifted out of SERIAL-OUT on the falling edge of CLOCK.

Marks: The latches hold data while the LATCH terminal is held Low. When the LATCH terminal is High, the latches do not hold data and pass it transparently. When the ENABLE terminal is Low, OUTO to OUT7 toggle between ON and OFF according to the data. When the ENABLE terminal is High, OUTO to OUT7 are forced OFF.

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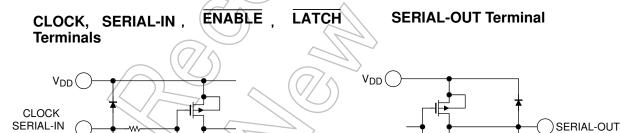
# **Terminal Description**

Pin No.	Pin Name	Function
1	GND	GND terminal
2	SERIAL-IN	Serial data input terminal
3	CLOCK	Serial clock input terminal
4	LATCH	Latch input terminal
5	OUT0	Constant-current output terminal (Open collector)
6	OUT1	Constant-current output terminal (Open collector)
7	OUT2	Constant-current output terminal (Open collector)
8	OUT3	Constant-current output terminal (Open collector)
9	OUT4	Constant-current output terminal (Open collector)
10	OUT5	Constant-current output terminal (Open collector)
11	OUT6	Constant-current output terminal (Open collector)
12	OUT7	Constant-current output terminal (Open collector)
13	ENABLE	Output enable input terminal All outputs (OUTO to OUT7) are disabled when the ENABLE terminal is driven High, and enabled when it is driven Low.
14	SERIAL-OUT	Serial data output terminal. Serial data is clocked out on the falling edge of CLOCK.
15	R-EXT	An external resistor is connected between this terminal and ground. OUT0 to OUT7 are adjusted to the same current value.
16	$V_{DD}$	Power supply terminal

# **Equivalent Circuits for Inputs and Outputs**

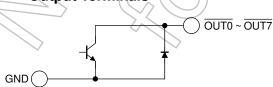
ENABLE LATCH

GND (



GND (





# **Absolute Maximum Ratings (Ta = 25°C)**

Characteristics	Symbol	Rating	Unit
Supply voltage	$V_{DD}$	6.0	V
Input voltage	V <sub>IN</sub>	-0.3 to V <sub>DD</sub> + 0.3 (Note 1)	V
Output current	lout	55	mA/ch
Output voltage	V <sub>OUT</sub>	-0.3 to 25	V
Power dissipation	P <sub>d</sub>	1.19(FG TYPE) / 1.02(FNG TYPE) (Notes 2 and 3)	W
Thermal resistance	R <sub>th (j-a)</sub>	105(FG TYPE) / 122(FNG TYPE) (Note 2)	°C/W
Operating temperature range	T <sub>opr</sub>	-40 to 85	°C
Storage temperature range	T <sub>stg</sub>	-55 to 150	°C
Maximum junction temperature	Tj	150	°C

Note 1: However, do not exceed 6.0 V.

Note 2: When mounted on a PCB (76.2  $\times$  114.3  $\times$  1.6 mm; Cu = 30%; 35- $\mu$ m-thick; SEMI-compliant)

Note 3: Power dissipation is reduced by 1/R<sub>th (j-a)</sub> for each °C above 25°C ambient.

# Operating Ranges (unless otherwise specified, Ta = -40°C to 85°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Supply voltage	$V_{DD}$	_ ( ( / / <	3	_	5.5	V
Output voltage	V <sub>OUT</sub>	OUT0 to OUT7	0.4	_	4	V
	lout	OUTO to OUT7	5	_	40	mA/ch
Output current	Гон	SERIAL-OUT	_		-5	mA
	lor	SERIAL-OUT	_		5	IIIA
	(V <sub>IH</sub> )	SERIAL-IN/CLOCK	$\begin{array}{c} 0.7 \times \\ V_{DD} \end{array}$	I	V <sub>DD</sub>	- V
Input voltage	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	LATCH / ENABLE	GND		0.3 × V <sub>DD</sub>	
Clock frequency	fcLK	Cascade connection	_		25	MHz
LATCH pulse width	t <sub>wLAT</sub>	(Note 2)	20		_	ns
CLOCK pulse width	twckK	(Note 2)	20		_	115
ENADLE auto Otable		$I_{OUT} \ge 20 \text{ mA}$ (Note 2)	2		_	
ENABLE pulse width	t <sub>wENA</sub>	$5 \text{ mA} \le I_{OUT} \le 20 \text{ mA}$ (Note 2)	3		_	μS
Setup time	<sup>t</sup> SETUP1		5		_	
Setup time	tSETUP2	(Note 2)	5		_	ns
Hold time	tHOLD1	(Note 2)	5		_	115
Tiold time	tHOLD2		5			
Maximum clock rise time	t <sub>r</sub>	Single operation (Notes 1 and 2)	_	_	5	6
Maximum clock fall time	√ t <sub>f</sub>	Tolligie operation (Notes i and 2)	_	_	5	μS

Note 1: For cascade operation, the CLOCK waveform might become ambiguous, causing the  $t_r$  and  $t_f$  values to be large. Then it may not be possible to meet the timing requirement for data transfer. Please consider the timing carefully.

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Note 2: Please see the timing waveform on page 9.

# Electrical Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 4.5$ to 5.5 V)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output current	l <sub>OUT1</sub>	5	$V_{OUT} = 0.4 \text{ V}, \text{ R-EXT} = 1.2 \text{ k}\Omega$ $V_{DD} = 5 \text{ V},$	_	15	_	mA
Output current error between ICs	Δl <sub>OUT1</sub>	5	$V_{OUT} = 0.4$ V, R-EXT = 1.2 k $\Omega$ All channels ON $V_{DD} = 5$ V,	-	±3	±6	%
Output current error between channels	Δl <sub>OUT2</sub>	5	$V_{OUT}$ = 0.4 V, R-EXT = 1.2 k $\Omega$ All channels ON $V_{DD}$ = 5 V	7	±1	±3	%
Output leakage current	l <sub>OZ</sub>	5	V <sub>OUT</sub> = 25 V		_	1	μА
Input voltage	V <sub>IH</sub>	_	SERIAL-IN/CLOCK/LATCH	0.7 × V <sub>DD</sub>	_	V <sub>DD</sub>	V
	V <sub>IL</sub>	_	SERIAL-IN/CLOCK/LATCH / ENABLE	GND	_	0.3 × V <sub>DD</sub>	V
	l <sub>IH</sub>	2	V <sub>IN</sub> = V <sub>DD</sub> CLOCK/SERIAL-IN / LATCH / ENABLE	-<		, 1	μА
Input current	I <sub>IL</sub>	3	V <sub>IN</sub> = GND CLOCK/SERIAL-IN/ LATCH / ENABLE			-1	
SERIAL-OUT output voltage	V <sub>OL</sub>	1	I <sub>OL</sub> = 5.0 mA, V <sub>DD</sub> = 5 V	P		0.3	V
	$V_{OH}$	1	$I_{OH} = -5.0 \text{ mA}, V_{DD} = 5 \text{ V}$	4.7	_	_	
Changes in constant output current dependent on V <sub>DD</sub>	%/V <sub>DD</sub>	5	V <sub>DD</sub> = 3 V to 5.5 V	_	1	2	%
	I <sub>DD (OFF) 1</sub>	4	R-EXT = OPEN, V <sub>OUT</sub> = 25.0 V	_	_	1	
Supply current	I <sub>DD</sub> (OFF) 2	4	R-EXT = 1.2 k $\Omega$ , V <sub>OUT</sub> = 25.0 V, All channels OFF	_	_	5	mA
	IDD (ON)	1/4	R-EXT = 1.2 k $\Omega$ , V $_{OUT}$ = 0.4 V, All channels ON		_	9	

# Switching Characteristics (Unless otherwise specified, Ta = 25°C, V<sub>DD</sub> = 4.5 to 5.5V)

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Characteristics	Symbol	Test Circuit	Test Condition (Note 1)	Min	Тур.	Max	Unit
	t <sub>pLH1</sub>	6	CLK-OUTn , LATCH = "H", ENABLE = "L"	_	20	300	
	t <sub>pLH2</sub>	6	ENABLE = "L"	_	20	300	
	t <sub>pLH3</sub>	6	ENABLE – OUTn , LATCH = "H"	_	20	300	ns
Propagation dollay time	tpLH	6	CLK-SERIAL OUT	2	10	14	
Propagation delay time	tpHL1	6	CLK- OUTn , LATCH = "H", ENABLE = "L"	_	30	340	
	t <sub>pHL2</sub>	6	LATCH – OUTn , ENABLE = "L"	_	70	340	
	t <sub>pHL3</sub>	6	ENABLE – OUTn , LATCH = "H"	_	70	340	
	t <sub>pHL</sub>	6	CLK-SERIAL OUT	2	10	14	
Output rise time	t <sub>or</sub>	6	10% to 90% points of OUT0 to OUT7 voltage waveforms	_	20	150	
Output fall time	t <sub>of</sub>	6	90% to 10% points of OUT0 to OUT7 voltage waveforms	_	125.	300	

Note 1:  $T_{opr} = 25$ °C,  $V_{DD} = V_{IH} = 5$  V,  $V_{IL} = 0$  V,  $R_{EXT} = 1.2$  k $\Omega$ ,  $I_{OUT} = 15$  mA,  $V_L = 5.0$  V,  $C_L = 10.5$  pF (see test circuit 6.)

# Electrical Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 3$ to 3.6 V)

Characteristics	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Output current	l <sub>OUT1</sub>	5	$V_{OUT}$ = 0.4 V, R-EXT = 1.2 k $\Omega$ $V_{DD}$ = 3.3 V	_	15	_	mA
Output current error between ICs	Δl <sub>OUT1</sub>	5	$V_{OUT}$ = 0.4 V, R-EXT = 1.2 k $\Omega$ All channels ON $V_{DD}$ = 3.3 V	-	±3	±6	%
Output current error between channels	Δl <sub>OUT2</sub>	5	$V_{OUT} = 0.4$ V, R-EXT = 1.2 k $\Omega$ All channels ON $V_{DD} = 3.3$ V	7	±1	±3	%
Output leakage current	l <sub>OZ</sub>	5	V <sub>OUT</sub> = 25 V		_	1	μА
Input voltage	V <sub>IH</sub>		SERIAL-IN/CLOCK/LATCH	0.7 × V <sub>DD</sub>	_	V <sub>DD</sub>	V
	$V_{IL}$	_	SERIAL-IN/CLOCK/LATCH ) ENABLE	GND	_	$^{0.3\times}_{V_{DD}}$	V
	I <sub>IH</sub>	2	V <sub>IN</sub> = VDD CLOCK/SERIAL-IN/ LATCH / ENABLE	W		) 1	μА
Input current	I <sub>IL</sub>	3	V <sub>IN</sub> = GND CLOCK/SERIAL-IN/ LATCH / ENABLE		<i>(</i> )	-1	
SERIAL-OUT output voltage	$V_{OL}$	1	$I_{OL} = 5.0 \text{ mA}, V_{DD} = 3.3 \text{ V}$	\{\tag{\tag{\tag{\tag{\tag{\tag{\ta	_	0.3	V
	$V_{OH}$	1	$I_{OH} = -5.0 \text{ mA}, V_{DD} = 3.3 \text{ V}$	3.0	_	_	
Changes in constant output current dependent on V <sub>DD</sub>	%/V <sub>DD</sub>	5	V <sub>DD</sub> = 3 V to 5.5 V	_	1	2	%
Supply current	I <sub>DD</sub> (OFF) 1	4	R-EXT = OPEN, V <sub>OUT</sub> = 25.0 V	_	_	1	
	IDD (OFF) 2	)4	R-EXT = 1.2 k $\Omega$ , V <sub>OUT</sub> = 25.0 V, All channels OFF	_	_	5	mA
	IDD (ON)	4	R-EXT = 1.2 k $\Omega$ , V <sub>OUT</sub> = 0.4 V, All channels ON	ı	_	9	

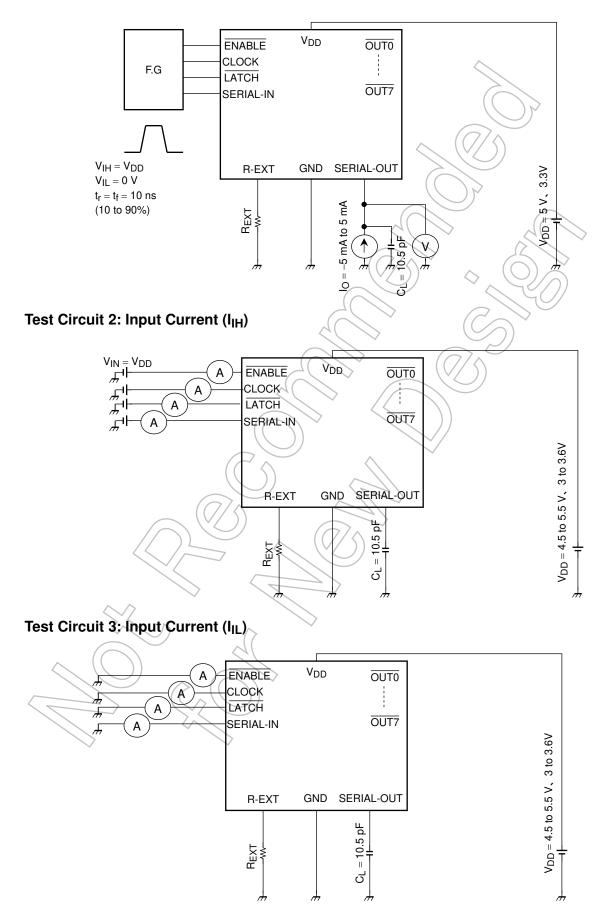
# Switching Characteristics (Unless otherwise specified, Ta = 25°C, $V_{DD} = 3$ to 3.6 V)

Characteristics	Symbol	Test Circuit	Test Condition (Note 1)	Min	Тур.	Max	Unit
	t <sub>pLH1</sub>	6	CLK-OUTn , LATCH = "H", ENABLE = "L"			300	
$\sim$	t <sub>pLH2</sub>	6	ENABLE = "L"			300	
	t <sub>p</sub> LH3	6	ENABLE - OUTn , LATCH = "H"	_		300	
Propagation delay time	tpLH	6	CLK-SERIAL OUT	2	_	14	
Propagation delay-time	tpHL1	6	CLK- OUTn , LATCH = "H", ENABLE = "L"			340	ns
	t <sub>pHL2</sub>	6	LATCH - OUTn , ENABLE = "L"		_	340	
	t <sub>pHL3</sub>	6	ENABLE - OUTn , LATCH = "H"	_	_	340	
	t <sub>pHL</sub>	6	CLK-SERIAL OUT	2	_	14	
Output rise time	t <sub>or</sub>	6	10% to 90% points of OUT0 to OUT7 voltage waveforms			150	
Output fall time	t <sub>of</sub>	6	90% to 10% points of OUT0 to OUT7 voltage waveforms	_	_	300	

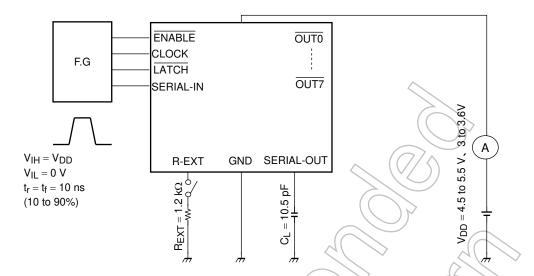
Note 1:  $T_{opr} = 25$ °C,  $V_{DD} = V_{IH} = 3.3$  V,  $V_{IL} = 0$  V,  $R_{EXT} = 1.2$  k $\Omega$ ,  $I_{OUT} = 15$  mA,  $V_{L} = 5.0$  V,  $C_{L} = 10.5$  pF (see test circuit 6.)

### **Test Circuits**

# Test Circuit 1: SERIAL-OUT output voltage (V<sub>OH</sub>/V<sub>OL</sub>)

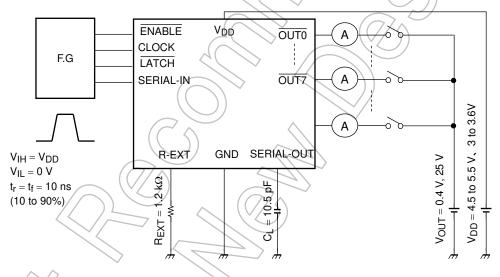


**Test Circuit 4: Supply Current** 



Note: The output terminal is based on the power supply current conditions on page 6 and 7.

Test Circuit 5: Output Current (I<sub>OUT1</sub>), Output Leakage Current (I<sub>OZ</sub>), Output Current Error Margin (ΔI<sub>OUT1</sub>/ΔI<sub>OUT2</sub>), Current Variation with V<sub>DD</sub> (%/V<sub>DD</sub>)

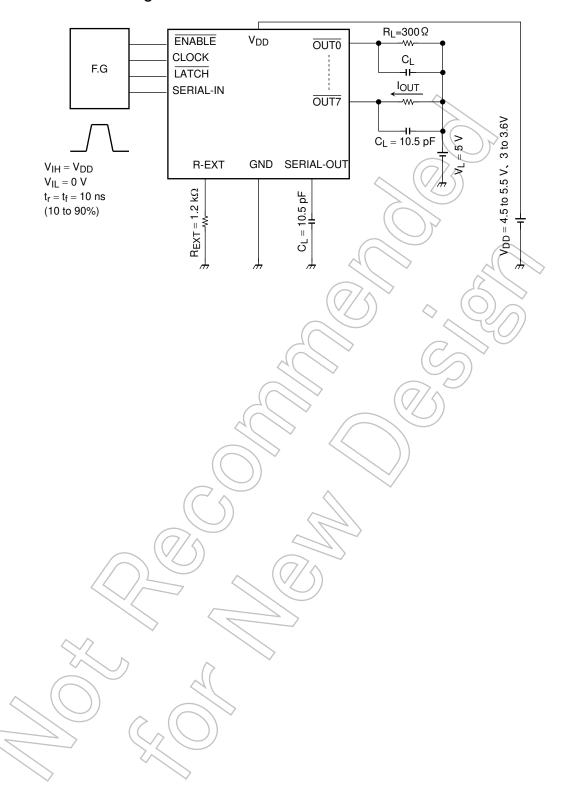


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Theoretical output current =  $1.13 \text{ V/R}_{EXT} \times 16$ 

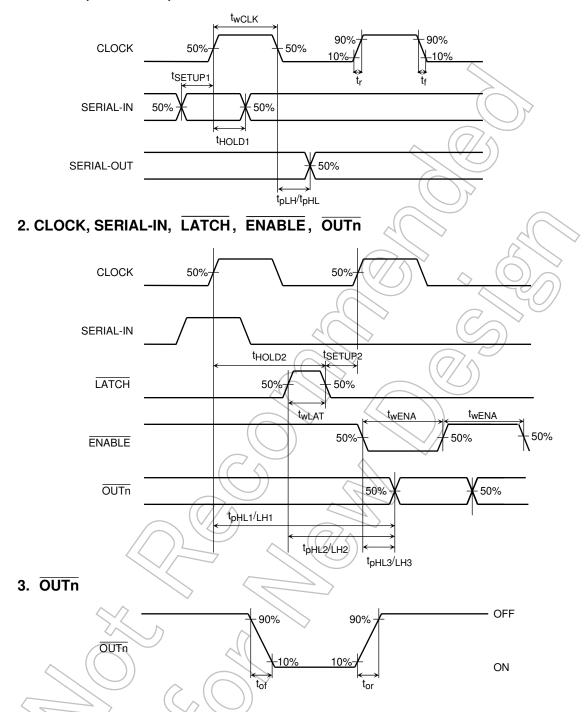


# **Test Circuit 6: Switching Characteristics**



# **Timing Waveforms**

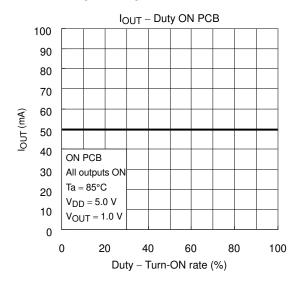
### 1. CLOCK, SERIAL-IN, SERIAL-OUT

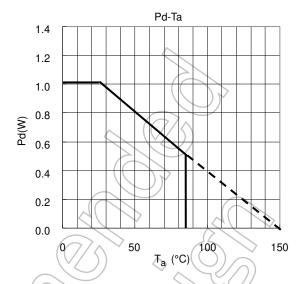


Note: Timing chart waveforms are presented to describe functions and operations and may be simplified. Adequate consideration should be given to timing conditions.

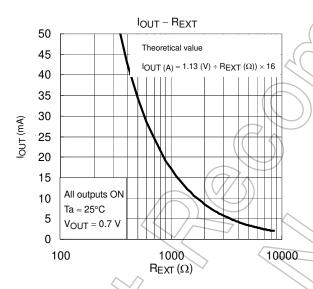
# **Output Current vs. Derating (lighting rate) Graph**

PCB Conditions:  $76.2\times114.3\times1.6$  mm, Cu = 30%, 35- $\mu m$  Thick, SEMI-Compliant TB62777FNG





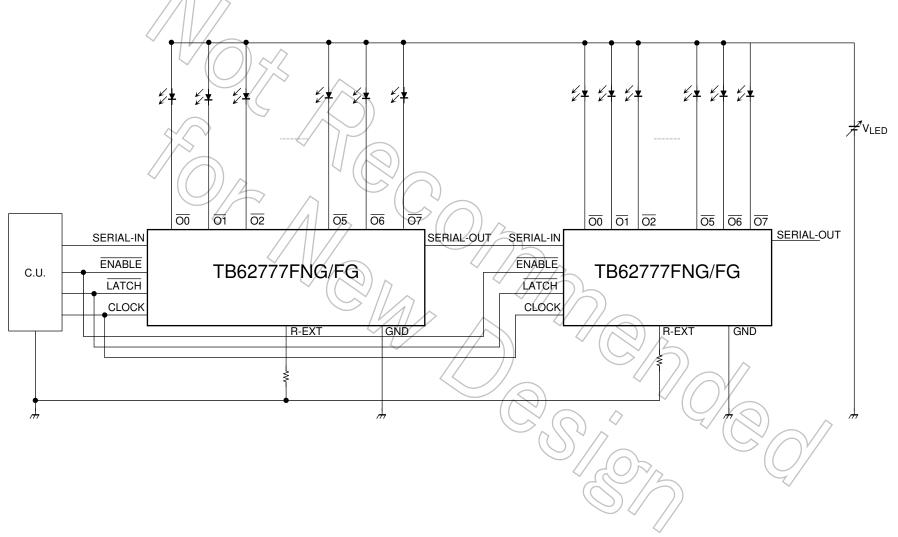
# Output Current vs. External Resistor (typ.)



The above graphs are presented merely as a guide and do not constitute any guarantee as to the performance or characteristics of the device. Each product design should be fully evaluated in a real-world environment.

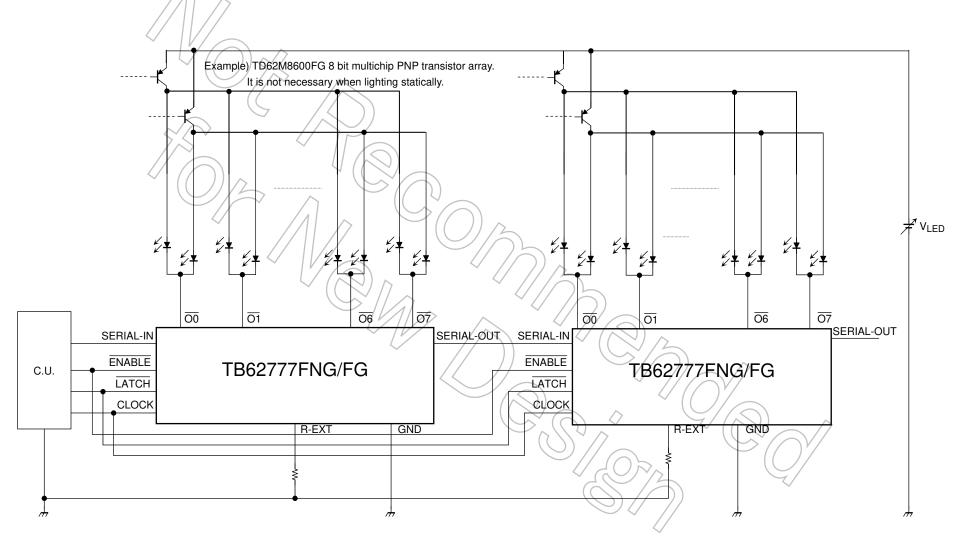
# **Application Circuit 1: General Composition for Static Lighting of LEDs**

In the following diagram, it is recommended that the LED supply voltage ( $V_{LED}$ ) be equal to or greater than the sum of  $V_f$  (max) of all LEDs plus 0.7 V.

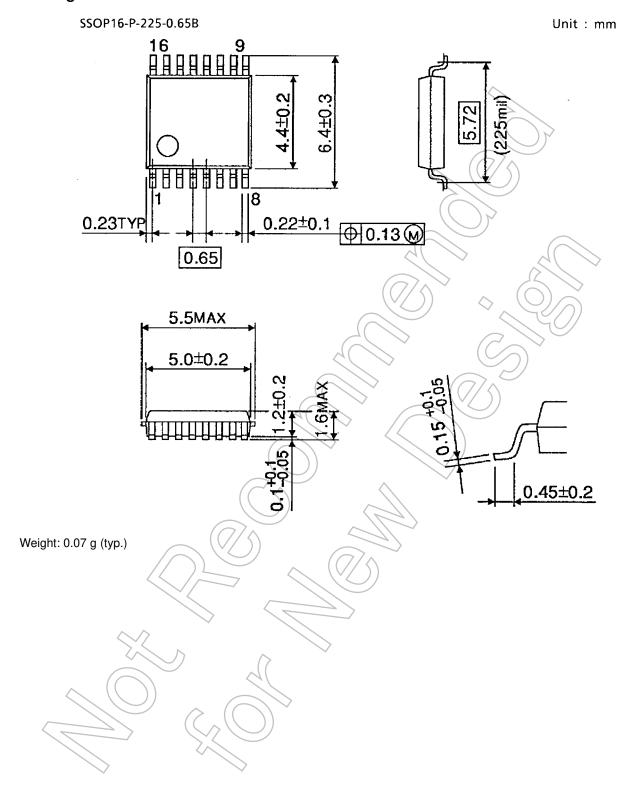


# **Application Circuit 2: General Composition for Dynamic Lighting of LEDs**

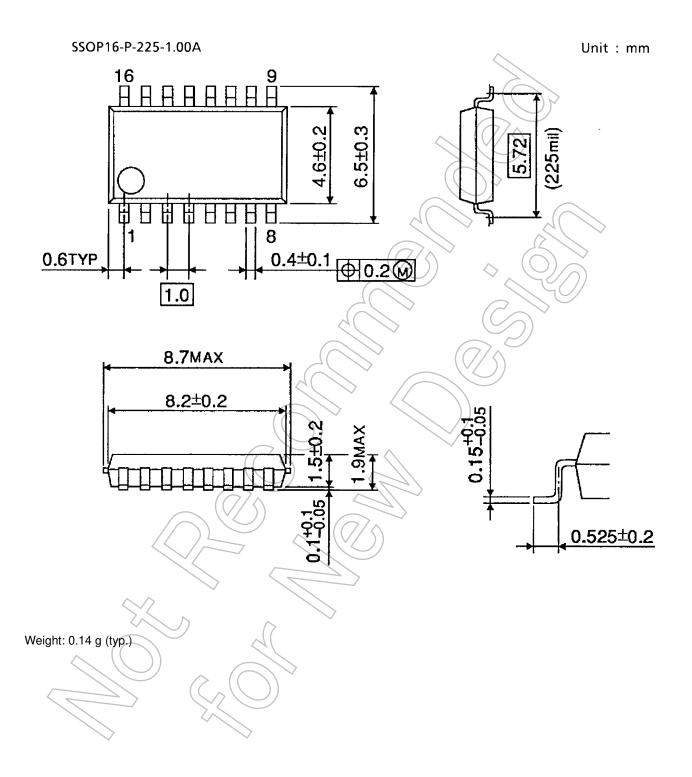
In the following diagram, it is recommended that the LED supply voltage ( $V_{LED}$ ) be equal to or greater than the sum of  $V_f$  (max) of all LEDs plus 0.7 V.



# **Package Dimensions**



# **Package Dimensions**



### **Notes on Contents**

### 1. Block Diagrams

Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

### 2. Equivalent Circuits

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

### 3. Timing Charts

Timing charts may be simplified for explanatory purposes.

### 4. Application Circuits

The application circuits shown in this document are provided for reference purposes only. Thorough evaluation is required, especially at the mass production design stage.

Toshiba does not grant any license to any industrial property rights by providing these examples of application circuits.

### 5. Test Circuits

Components in the test circuits are used only to obtain and confirm the device characteristics. These components and circuits are not guaranteed to prevent malfunction or failure from occurring in the application equipment.

### IC Usage Considerations

### Notes on handling of ICs

- (1) The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.
  Exceeding the rating(s) may cause breakdown, damage or deterioration of the device, and may result in injury by explosion or combustion.
- (2) Use an appropriate power supply fuse to ensure that a large current does not continuously flow in the event of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow. Such a breakdown can lead to smoke or ignition. To minimize the effects of a large current flow in the event of breakdown, fuse capacity, fusing time, insertion circuit location, and other such suitable settings are required.
- (3) If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. IC breakdown may cause injury, smoke or ignition.
  - For ICs with built-in protection functions, use a stable power supply with. An unstable power supply may cause the protection function to not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- (4) Do not insert devices incorrectly or in the wrong orientation. Make sure that the positive and negative terminals of power supplies are connected properly. Otherwise, the current or power consumption may exceed the absolute maximum rating, and exceeding the rating(s) may cause breakdown, damage or deterioration of the device, which may result in injury by explosion or combustion. In addition, do not use any device that has had current applied to it while inserted incorrectly or in the wrong orientation even once.

(5) Carefully select power amp, regulator, or other external components (such as inputs and negative feedback capacitors) and load components (such as speakers).

If there is a large amount of leakage current such as input or negative feedback capacitors, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

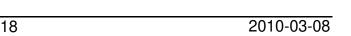
### Points to remember on handling of ICs

(1) Heat Dissipation Design

In using an IC with large current flow such as a power amp, regulator or driver, please design the device so that heat is appropriately dissipated, not to exceed the specified junction temperature (Tj) at any time or under any condition. These ICs generate heat even during normal use. An inadequate IC heat dissipation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into consideration the effect of IC heat dissipation on peripheral components..

(2) Back-EMF

When a motor rotates in the reverse direction, stops, or slows down abruptly, a current flow back to the motor's power supply due to the effect of back-EMF. If the current sink capability of the power supply is small, the device's motor power supply and output pins might be exposed to conditions beyond maximum ratings. To avoid this problem, take the effect of back-EMF into consideration in your system design.



About solderability, following conditions were confirmed

- Solderability
  - (1) Use of Sn-37Pb solder Bath
    - · solder bath temperature = 230°C
    - · dipping time = 5 seconds
    - the number of times = once
    - · use of R-type flux
  - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
    - · solder bath temperature = 245°C
    - · dipping time = 5 seconds
    - the number of times = once
      use of R-type flux



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